**IN THE CLAIMS:** 

1. (Original) A method of manufacturing a layered silicone composite material comprising

the steps of:

applying a second addition-curable organopolysiloxane composition that

contains a second adhesion promoter onto a first silicone layer that is formed by

curing a first addition-curable organopolysiloxane composition containing a first

adhesion promoter and where the first silicone layer has a hardness of less than JIS A

50; and

forming a second silicone layer that has a hardness of JIS A 50 or more by

curing said second addition-curable organopolysiloxane composition.

2. (Cancelled)

3. (Previously Presented) The method according to Claim 1, where at least one of the first

adhesion promoter and the second adhesion promoter is an organosilicon compound

containing, per molecule, at least one alkoxy group, at least one alkoxyalkoxy group,

or both.

4. (Previously Presented) The method according to Claim 3, where at least one of the first

adhesion promoter and the second adhesion promoter contains at least one silicon-

bonded alkenyl group, at least one silicon-bonded hydrogen atom, or both.

5. (Previously Presented) The method according to Claim 3, where at least one of the first

adhesion promoter and the second adhesion promoter contains at least one epoxy

group.

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6. (Previously Presented) The method according to Claim 1, where at least one of the first addition-curable organopolysiloxane composition and the second addition-curable

organopolysiloxane composition is free of inorganic filler.

7. (Previously Presented) The method according to any of Claim 1, where the layered

silicone composite material is an optically transparent material.

8. (Previously Presented) The method according to any of Claim 1, where layered silicone

composite material is at least a part of an optical element.

9. (Previously Presented) The method according to Claim 4, where at least one of the first

adhesion promoter and the second adhesion promoter contains at least one epoxy

group.

10-16. (Cancelled)

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